



M T B F

(EIAJ RCR-9102B)

Model	SNDPF1000
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No.	Parts		Q'ty of Device	Failure rate [$10^{-6}/H$]	Reference
1	IC	Linear	1	0.0240	
2	Transistors	NPN/PNP	1	0.0011	
3	Diodes	FR	0	0.0000	
4	Diodes	switching	2	0.0150	
5	Diodes	Zener	1	0.0240	
6	Photoelectron Device	Photo-coupler	0	0.0000	
7	Resistors	Metal Film	11	0.1760	
8	Resistors	Carbon Film	0	0.0000	
9	Resistors	Power Film	4	0.1640	
10	Resistors	Temperature Fuse	2	0.1560	
11	Resistors	variable	0	0.0000	
12	Varistor	Varistor	2	0.0460	
13	Capacitors	Aluminum Electrolytic	5	0.0950	
14	Capacitors	Film	9	0.0756	
15	Capacitors	Ceramic	3	0.0780	
16	Coil	Line Filter	2	0.0009	
17	Coil	Ferrite Beads	0	0.0000	
18	Fuses		1	0.0200	
19	Switch	Toggle	1	0.5000	
20	Connectors	Printed Circuit Board	5	0.2600	
21	Connection	Hand Solder	9	0.0234	
22	Connection	Flow Solder	265	0.1378	
23	Connection	Screw	13	0.0130	
24	Printed Circuit Board	Through Hole	1	0.0450	
25	P S 1		1	2.8992	
Total Failure Rate [$10^{-6}/H$]				4.7540	

M T B F	[H]	210,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-